


MCT028D0W240320PMLIPS	240 x 320	Mutli Interface	TFT Module
(MDT0280A1IH-MULTI) Specification			
Version: 2		Date: 06/04/2021	
Revision			
1	29/09/2019	First issue	
2	06/04/2021	Small corrections	

Display Features			
Display Size	2.8"		
Resolution	240 x 320		
Orientation	Portrait		
Appearance	RGB		
Logic Voltage	3.3V		
Interface	Multi		
Brightness	500 cd/m ²		
Touchscreen	---		
Module Size	50.50 x 69.70 x 2.60mm		
Operating Temperature	-20°C ~ +70°C		
Pinout	50 way FFC		Box Quantity
Pitch	0.5mm	---	---

* - For full design functionality, please use this specification in conjunction with the SSD1305Z specification.(Provided Separately)

Display Accessories	
Part Number	Description
MPBV5 KIT	Interconnect board that converts a 50-way FFC to 50 crimp-wire connector.

Optional Variants	
Appearances	Voltage



Basic Specifications

* Description

This is a color active matrix TFT (Thin Film Transistor) LCD (liquid crystal display) that uses amorphous silicon TFT as a switching device. This module is composed of a Transmissive type TFT-LCD Panel, driver circuit, capacitance touch panel, back-light unit. The resolution of a 2.8" TFT-LCD contains 240x320 pixels, and can display up to 65K/262K colors.

1. TFT Features

General Information Items	Specification	Unit	Note
	Main Panel		
Display area(AA)	43.20(H)*57.60 (V) (2.8inch)	mm	-
Driver element	TFT active matrix	-	-
Display colors	65K/262K	colors	-
Number of pixels	240(RGB)*320	dots	-
TFT Pixel arrangement	RGB vertical stripe	-	-
Pixel pitch	0.180(H)*0.180(V)	mm	-
Viewing angle	ALL	o'clock	-
TFT Controller IC	ST7789V	-	-
LCM Interface	8/9/16/18 Bit MCU 3/4SPI+16/18Bit RGB 3/4 Line Serial	-	-
Touch mode	Transmissive/ Normally black	-	-
Operating temperature	-20~+70	°C	-
Storage temperature	-30~+80	°C	-
Module bonding technology	Use Tape bonding between LCM and CTP	-	-

2. CTP Features

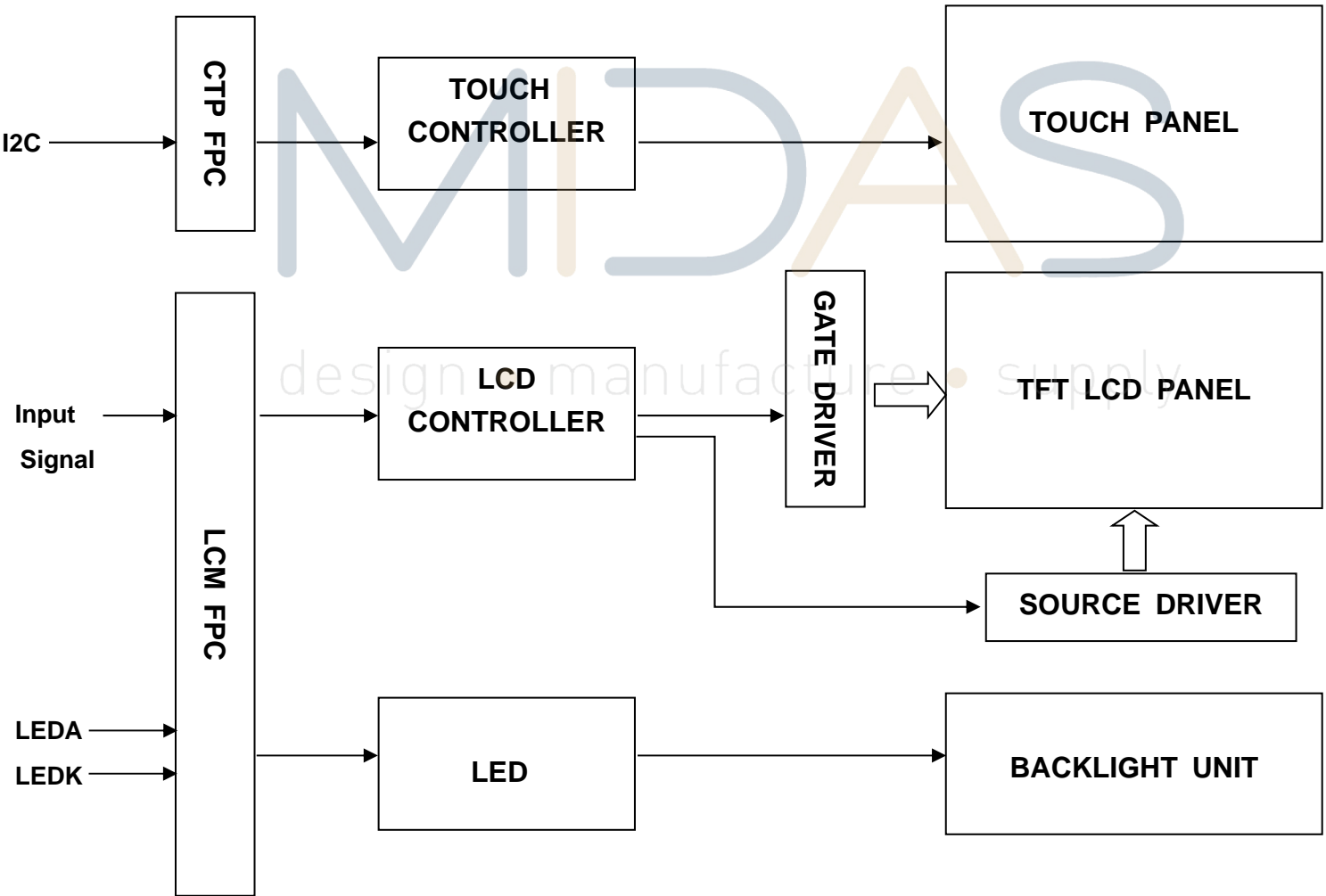
General Information Items	Specification	Unit	Note
	Main Panel		
Resolution	240(H)*320(V)	-	-
Structure	G+G	-	-
Controller IC	FT5436	-	-
Interface	I2C	-	-
Slave Address	0x38(7bit)/8bit:0x70(Write) 0x71(Read)	-	-
Touch mode	Five point and Gestures	-	-



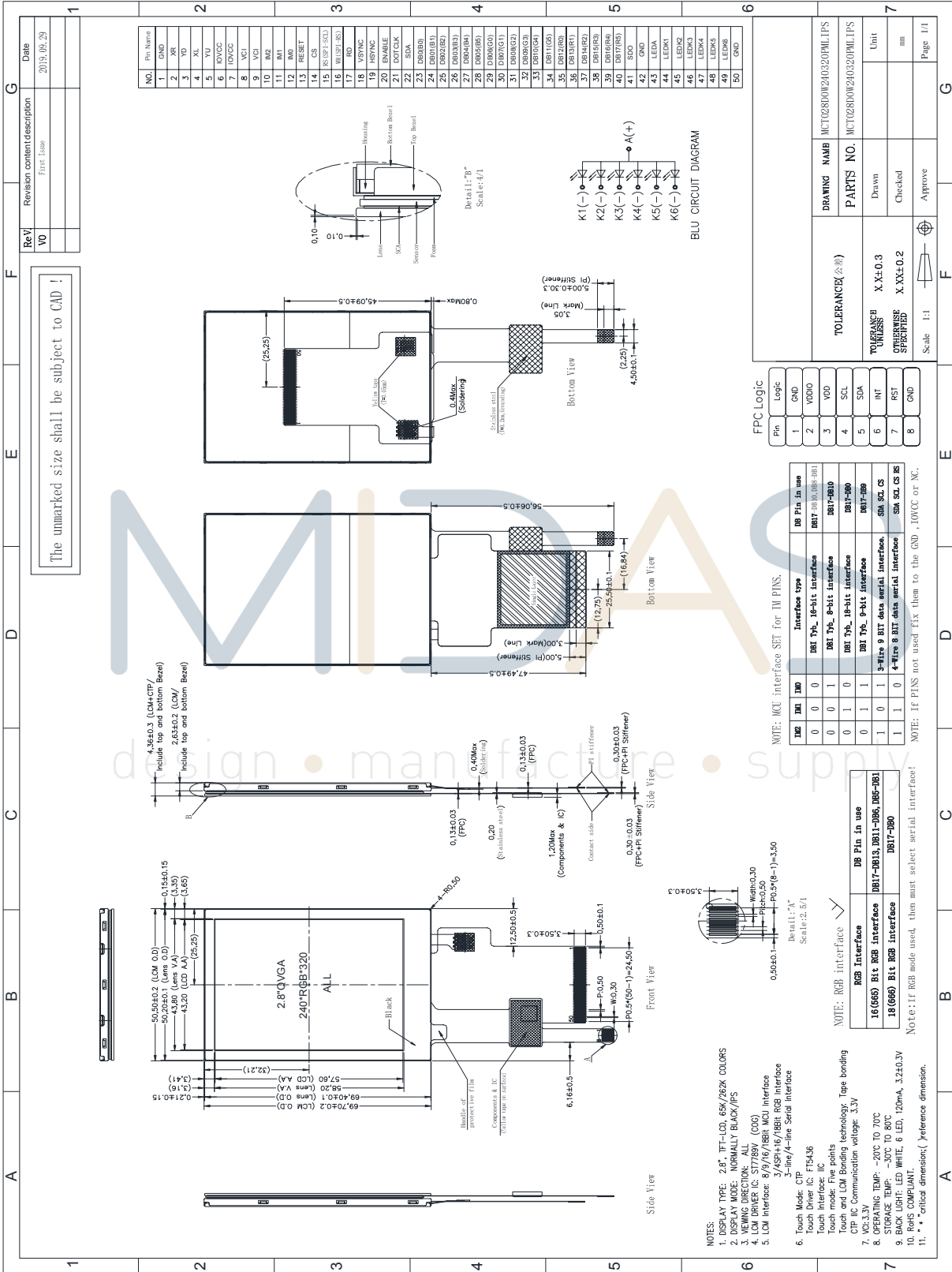
3. Mechanical Information

Item		Min.	Typ.	Max.	Unit	Note
Module size	Horizontal(H)		50.50		mm	-
	Vertical(V)		69.70		mm	-
	Depth(D)		4.36		mm	-
Weight			30		g	-

Block Diagram



Outline dimension



Input terminal Pin Assignment

1. TFT

NO.	SYMBOL	DISCRIPTION	I/O
1	GND	Ground.	P
2	XR(NC)	Touch panel Right Glass Terminal	A/D
3	YD(NC)	Touch panel Bottom Film Terminal	A/D
4	XL(NC)	Touch panel LIFT Glass Terminal	A/D
5	YU(NC)	Touch panel Top Film Terminal	A/D
6	IOVCC	Supply voltage for IO (1.65-3.3V).	P
7	IOVCC	Supply voltage for IO (1.65-3.3V).	P
8	VCI	Supply voltage (3.3V).	P
9	VCI	Supply voltage (3.3V).	P
10	IM2	MPU Parallel interface bus and serial interface select If use RGB Interface must select serial interface. Fix this pin at IOVCC and GND.	I
11	IM1		
12	IM0		
13	RESET	This signal will reset the device and must be applied to properly initialize the chip.	I
14	CS	Chip select input pin ("Low" enable). Fix this pin at IOVCC or GND when not in use.	I
15	RS(SPI-SCL)	This pin is used to select "Data or Command" in the parallel interface. When RS = '1', data is selected. When RS = '0', command is selected. This pin is used serial interface clock in 3-wire 9-bit / 4-wire 8-bit serial data interface. Fix this pin at IOVCC or GND when not in use.	I
16	WR(SPI-RS)	The data is applied on the rising edge of the SCL signal. Fix this pin at IOVCC or GND when not in use.	I
17	RD	Serves as a read signal and MCU read data at the rising edge. Fix this pin at IOVCC or GND when not in use	I
18	VSYNC	Frame synchronizing signal for RGB interface operation. Fix this pin at IOVCC or GND when not in use.	I
19	HSYNC	Line synchronizing signal for RGB interface operation. Fix this pin at IOVCC or GND when not in use.	I



20	ENABLE	Data enable signal for RGB interface operation. Fix this pin at IOVCC or GND when not in use.	I
21	DOTCLK	Dot clock signal for RGB interface operation. Fix this pin at IOVCC or GND when not in use.	I
22	SDA	Serial input signal. The data is applied on the rising edge of the SCL signal. If not used, fix this pin at IOVCC or GND.	I
23-40	DB0-DB17	Data bus. If not used pin, fix this pin to GND.	I/O
41	SDO	SPI interface output pin. -The data is output on the falling edge of the SCL signal. -If not used, let this pin open.	O
42	GND	Ground.	P
43	LEDA	Anode pin of backlight	P
44	LEDK1	Cathode pin OF backlight	P
45	LEDK2	Cathode pin OF backlight	P
46	LEDK3	Cathode pin OF backlight	P
47	LEDK4	Cathode pin OF backlight	P
48	LEDK5	Cathode pin OF backlight	P
49	LEDK6	Cathode pin OF backlight	P
50	GND	Ground.	P

2. CTP

NO.	SYMBOL	DISCRIPTION	I/O
1	GND	Ground.	P
2	VDDIO	I/O power supply voltage.	P
3	VDD	Supply voltage.	P
4	SCL	I2C clock input.	I
5	SDA	I2C data input and output	I/O
6	INT	External interrupt to the host.	I
7	RST	External Reset, Low is active.	I
8	GND	Ground.	P



LCD Optical Characteristics

1. Optical specification

Item	Symbol	Condition	Min.	Typ.	Max.	Unit.	Note
Contrast Ratio	CR	$\Theta=0$	600	800			(1)(2)
Response time	Rising	T_{R+T_F}	--	30	40	msec	(1)(3)
	Falling						
Color gamut	S(%)		60	65	--	%	
Color Filter Chromaticity	White	W_X	0.237	0.277	0.317	(1)(4) CF glass	
		W_Y	0.256	0.296	0.336		
	Red	R_X	0.577	0.617	0.657		
		R_Y	0.303	0.343	0.383		
	Green	G_X	0.261	0.301	0.341		
		G_Y	0.545	0.585	0.625		
	Blue	B_X	0.108	0.148	0.188		
		B_Y	0.012	0.052	0.092		
Viewing angle	Hor.	Θ_L	--	80	--	(1)(4) Measuring with Polarizer Reference Only	
		Θ_R	--	80	--		
	Ver.	Θ_U	--	80	--		
		Θ_D	--	80	--		
Option View Direction			FREE				(5)

2. Measuring Condition

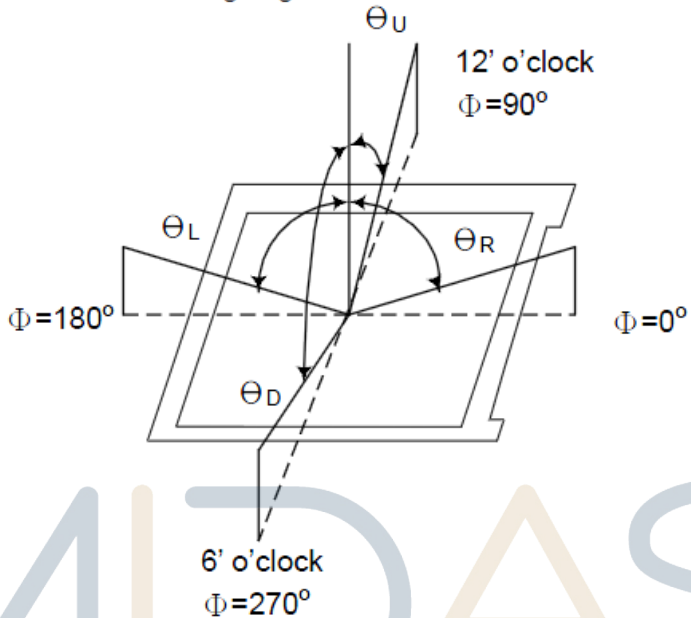
- Measuring surrounding: dark room
- Ambient temperature: $25\pm 2^\circ\text{C}$
- 15min. warm-up time.



3. Measuring Equipment

- FPM520 of Westar Display technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics.

Note (1) Definition of Viewing Angle:



MIDAS

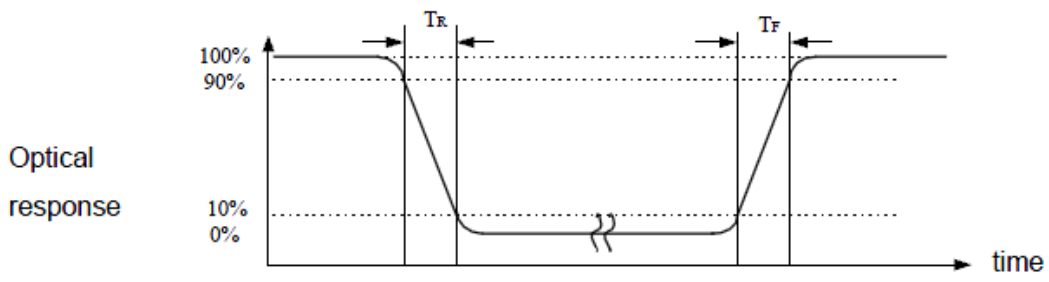
Note (2) Definition of Contrast Ratio (CR) :

measured at the center point of panel

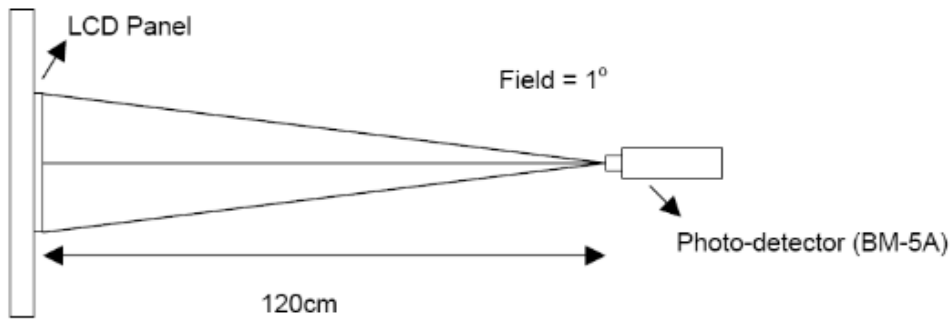
$$CR = \frac{\text{Luminance with all pixels white}}{\text{Luminance with all pixels black}}$$

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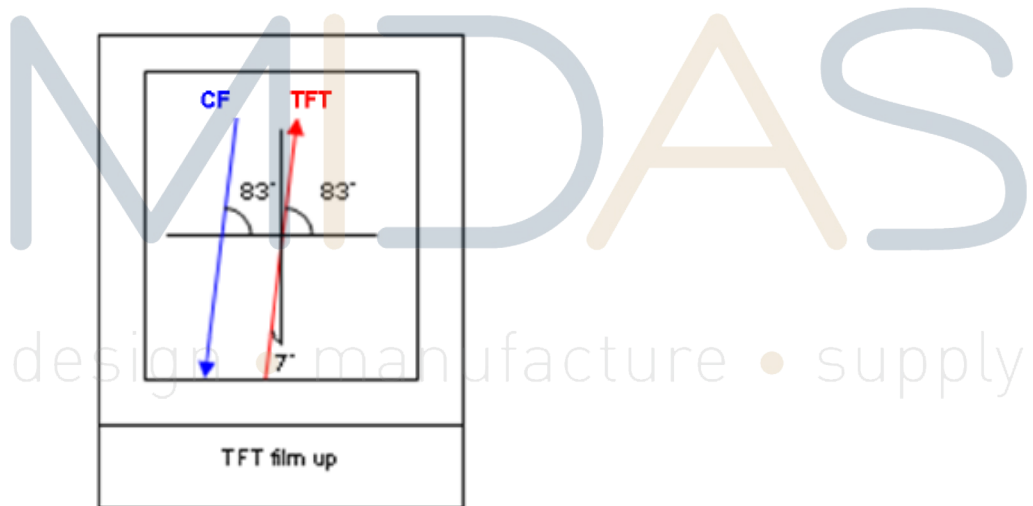
Note (3) Definition of Response Time : Sum of T_R and T_F



Note (4) Definition of optical measurement setup



Note (5) Rubbing Direction (The different Rubbing Direction will cause the different optima view direction.)



Electrical Characteristics

1. Absolute Maximum Rating (Ta=25 VSS=0V)

Characteristics	Symbol	Min.	Max.	Unit
Digital Supply Voltage	VCI/VDD	-0.3	4.6	V
Digital interface supply Voltage	IOVCC	-0.3	4.6	V
Operating temperature	T _{OP}	-20	+70	°C
Storage temperature	T _{ST}	-30	+80	°C

NOTE: If the absolute maximum rating of even is one of the above parameters is exceeded even momentarily, the quality of the product may be degraded. Absolute maximum ratings, therefore, specify the values exceeding which the product may be physically damaged. Be sure to use the product within the range of the absolute maximum ratings.

2. DC Electrical Characteristics

Characteristics	Symbol	Min.	Typ.	Max.	Unit	Note
Digital Supply Voltage	VCI/VDD	2.4	3.3	3.6	V	
Digital interface supply Voltage	IOVCC	1.65	1.8	3.3	V	
Normal mode Current consumption	IDD	--	8	16	mA	
Level input voltage	V _{IH}	0.7IOVCC		IOVCC	V	
	V _{IL}	GND		0.3IOVCC	V	
Level output voltage	V _{OH}	0.8IOVCC		IOVCC	V	
	V _{OL}	GND		0.2IOVCC	V	



3. LED Backlight Characteristics

The back-light system is edge-lighting type with 6 chips White LED

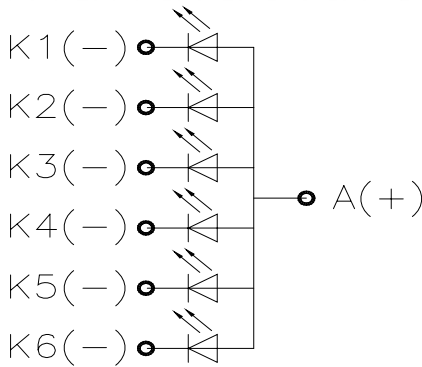
Item	Symbol	Min.	Typ.	Max.	Unit	Note
Forward Current	I_F	90	120	--	mA	
Forward Voltage	V_F	--	3.2	--	V	
LCM Luminance	L_V	550	600	--	cd/m ²	Note3
LED life time	Hr	50000	--	--	Hour	Note1,2
Uniformity	AVg	80	--	--	%	Note3

Note (1) LED life time (Hr) can be defined as the time in which it continues to operate under the condition:

$T_a=25\pm3\text{ }^\circ\text{C}$, typical IL value indicated in the above table until the brightness becomes less than 50%.

Note (2) The "LED life time" is defined as the module brightness decrease to 50% original brightness at $T_a=25\text{ }^\circ\text{C}$ and $I_L=120\text{mA}$. The LED lifetime could be decreased if operating I_L is larger than 120mA. The constant current driving method is suggested.

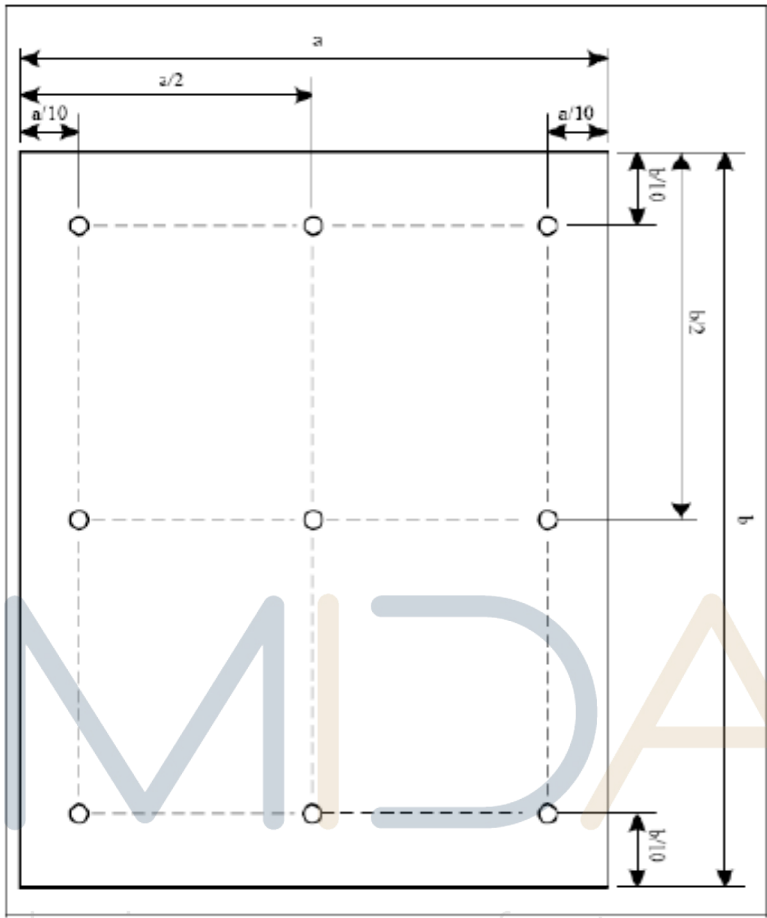
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BLU CIRCUIT DIAGRAM



NOTE 3: Luminance Uniformity of these 9 points is defined as below:



$$\text{Uniformity} = \frac{\text{minimum luminance in 9 points (1-9)}}{\text{maximum luminance in 9 points (1-9)}}$$

$$\text{Luminance} = \frac{\text{Total Luminance of 9 points}}{9}$$



AC Characteristic

1. 8080 Series MCU Parallel Interface Timing Characteristics: 18/16/9/8-bit Bus

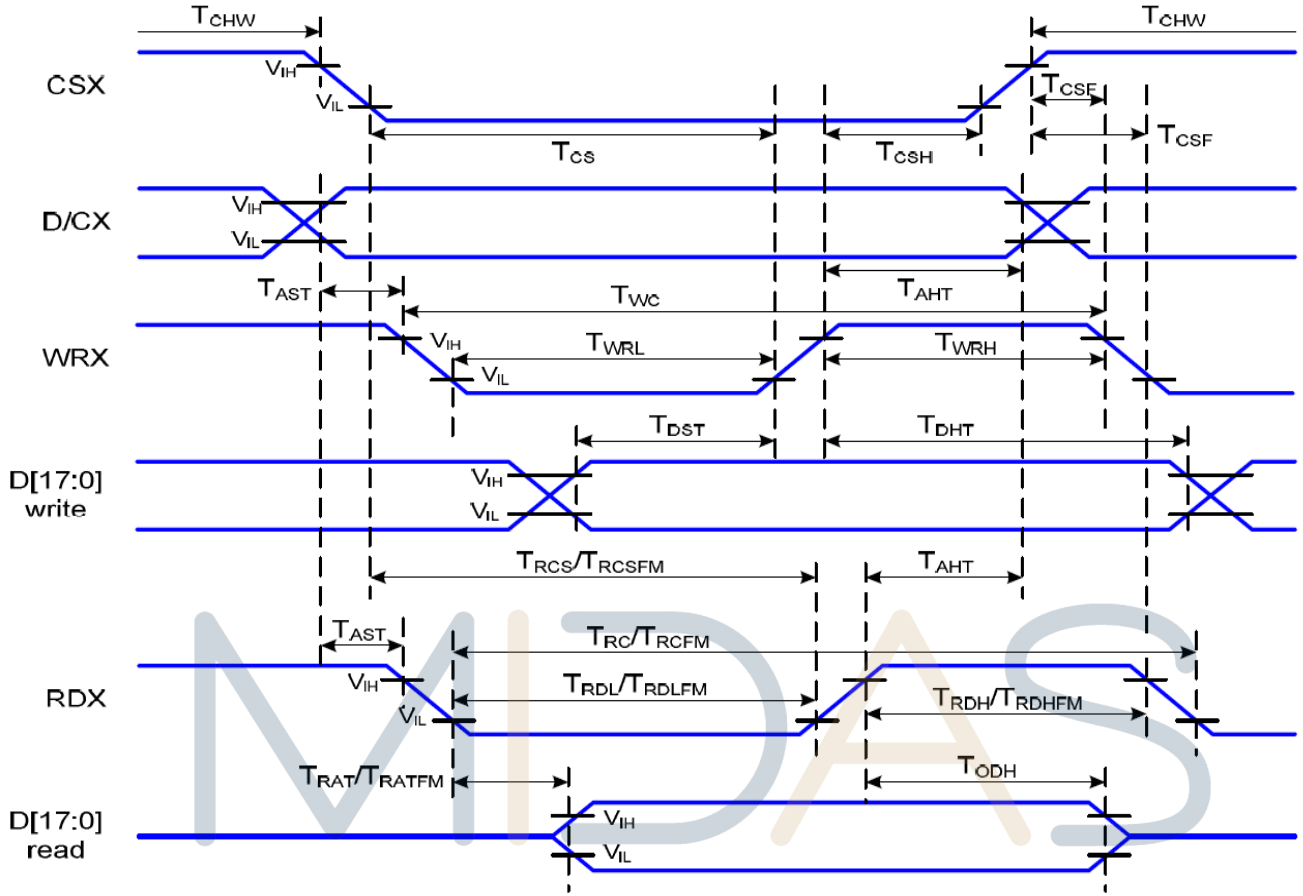


Figure6-1-1 Parallel Interface Timing Characteristics (8080-Series MCU Interface)

$V_{DD1}=1.65$ to $3.3V$, $V_{DD}=2.4$ to $3.3V$, $AGND=DGND=0V$, $T_a=-30$ to 70 °C

Signal	Symbol	Parameter	Min	Max	Unit	Description
D/CX	T_{AST}	Address setup time	0		ns	
	T_{AHT}	Address hold time (Write/Read)	10		ns	
CSX	T_{CHW}	Chip select "H" pulse width	0		ns	
	T_{CS}	Chip select setup time (Write)	15		ns	
	T_{RCS}	Chip select setup time (Read ID)	45		ns	
	T_{RCSFM}	Chip select setup time (Read FM)	355		ns	
	T_{CSF}	Chip select wait time (Write/Read)	10		ns	
	T_{CSH}	Chip select hold time	10		ns	
WRX	T_{WC}	Write cycle	66		ns	

	T_{WRH}	Control pulse "H" duration	15		ns	
	T_{WRL}	Control pulse "L" duration	15		ns	
RDX(ID)	T_{RC}	Read cycle (ID)	160		ns	When read ID data
	T_{RDH}	Control pulse "H" duration (ID)	90		ns	
	T_{RDL}	Control pulse "L" duration (ID)	45		ns	
RDX(FM)	T_{RCFM}	Read cycle (FM)	450		ns	When read from frame memory
	T_{RDHFM}	Control pulse "H" duration(FM)	90		ns	
	T_{RDLFM}	Control pulse "L" duration(FM)	355		ns	
DB[17:0]	T_{DST}	Data setup time	10		ns	For CL=30pF
	T_{DHT}	Data hold time	10		ns	
	T_{RAT}	Read access time (ID)		40	ns	
	T_{RATFM}	Read access time (FM)		340	ns	
	T_{ODH}	Output disable time	20	80	ns	

Table6-1-1 8080 Parallel Interface Characteristics

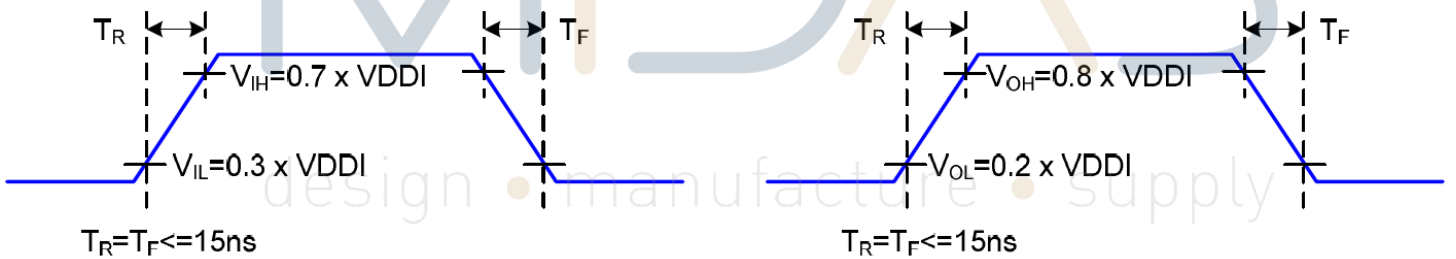


Figure6-1-2 Rising and Falling Timing for I/O Signal

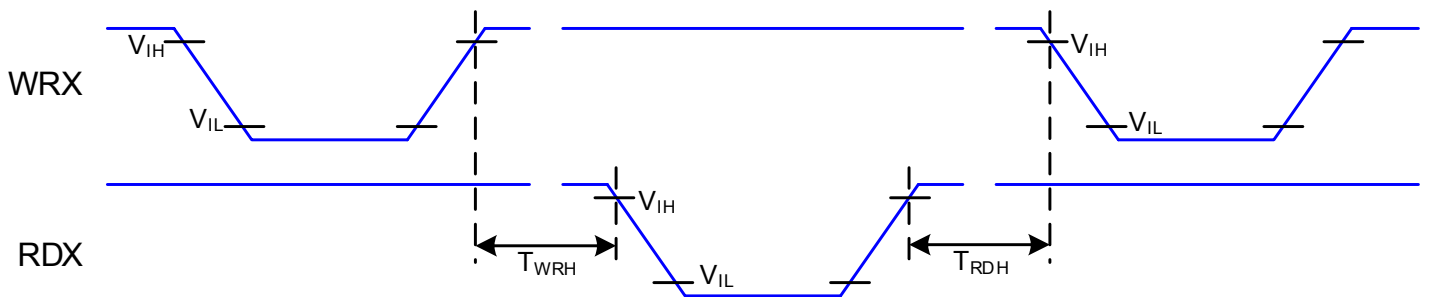


Figure6-1-3 Write-to-Read and Read-to-Write Timing

Note: The rising time and falling time (T_r , T_f) of input signal and fall time are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

2. Display Serial Interface Timing Characteristics (3-line SPI system)

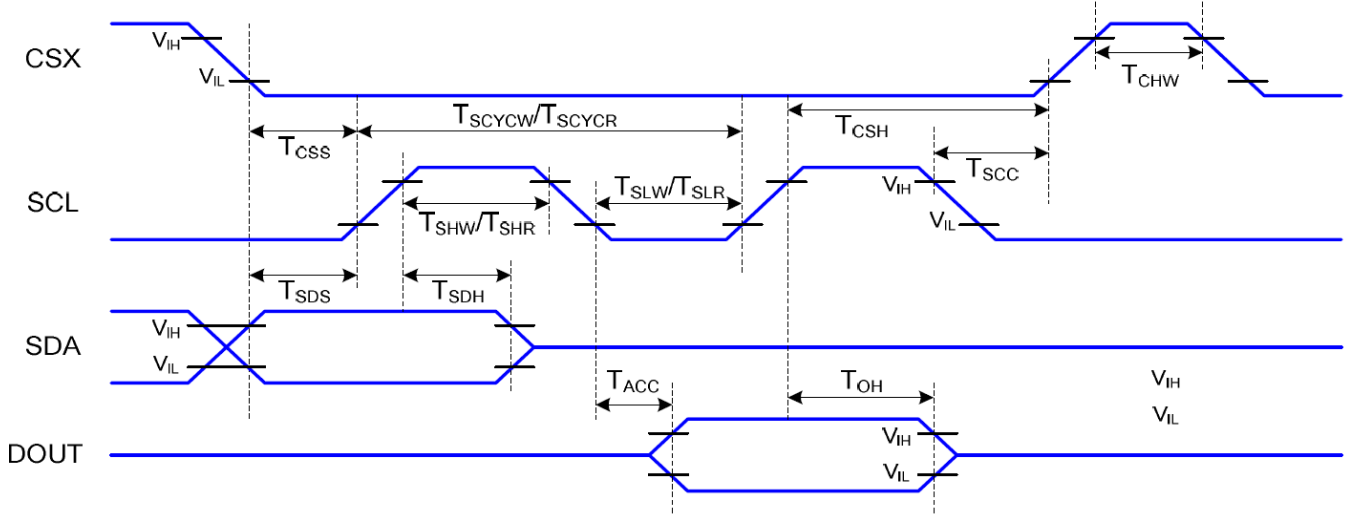


Figure6-2-1 3-line serial Interface Timing Characteristics

$V_{DDI}=1.65$ to $3.3V$, $V_{DD}=2.4$ to $3.3V$, $AGND=DGND=0V$, $T_a= -30$ to 70 °C

Signal	Symbol	Parameter	Min	Max	Unit	Description
CSX	T_{CSS}	Chip select setup time (Write)	15		ns	
	T_{CSH}	Chip select hold time (write)	15		ns	
	T_{CSS}	Chip select setup time (read)	60		ns	
	T_{SCC}	Chip select hold time (read)	65		ns	
	T_{CHW}	Chip select "H" pulse width	40		ns	
SCL	T_{SCYCW}	Serial clock cycle (Write)	66		ns	
	T_{SHW}	SCL "H" pulse width (Write)	15		ns	
	T_{SLW}	SCL "L" pulse width (Write)	15		ns	
	T_{SCYCR}	Serial clock cycle (Read)	150		ns	
	T_{SHR}	SCL "H" pulse width (Read)	60		ns	
	T_{SLR}	SCL "L" pulse width (Read)	60		ns	
SDA (DIN)	T_{SDS}	Data setup time	10		ns	
	T_{SDH}	Data hold time	10		ns	
DOUT	T_{ACC}	Access time	10	50	ns	For maximum $CL=30pF$
	T_{OH}	Output disable time	15	50	ns	For minimum $CL=8pF$

Table6-2-1 3-line serial Interface Characteristics

Note: The rising time and falling time (T_r , T_f) of input signal are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of V_{DDI} for Input signals.



3. Display Serial Interface Timing Characteristics (4-line SPI system)

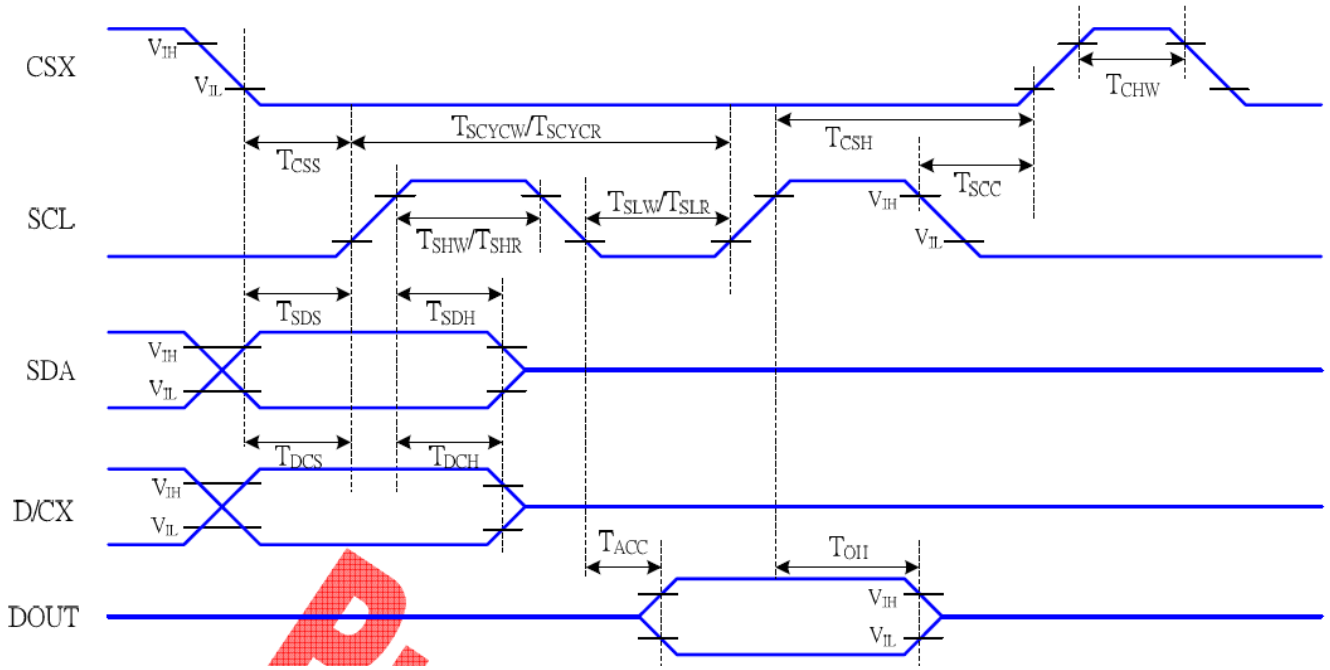


Figure6-3-1 4-line serial Interface Timing Characteristics

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta= -30 to 70 °C

Signal	Symbol	Parameter	Min	Max	Unit	Description
CSX	T_{CSS}	Chip select setup time (Write)	15		ns	
	T_{CSH}	Chip select hold time (write)	15		ns	
	T_{CSS}	Chip select setup time (read)	60		ns	
	T_{SCC}	Chip select hold time (read)	65		ns	
	T_{CHW}	Chip select "H" pulse width	40		ns	
SCL	T_{SCYCW}	Serial clock cycle (Write)	66		ns	-write command & data ram
	T_{SHW}	SCL "H" pulse width (Write)	15		ns	
	T_{SLW}	SCL "L" pulse width (Write)	15		ns	
	T_{SCYCR}	Serial clock cycle (Read)	150		ns	-read command & data ram
	T_{SHR}	SCL "H" pulse width (Read)	60		ns	
	T_{SLR}	SCL "L" pulse width (Read)	60		ns	
D/CX	T_{DCS}	D/CX setup time	10		Ns	
	T_{DCH}	D/CX hold time	10		ns	
SDA	T_{SDS}	Data setup time	10		ns	
(DIN)	T_{SDH}	Data hold time	10		ns	
DOUT	T_{ACC}	Access time	10	50	ns	For maximum CL=30pF For minimum CL=8pF
	T_{OH}	Output disable time	15	50	ns	

Table6-2-1 4-line serial Interface Characteristics

Note: The rising time and falling time (T_r , T_f) of input signal are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.



4. Parallel RGB Interface Timing Characteristics

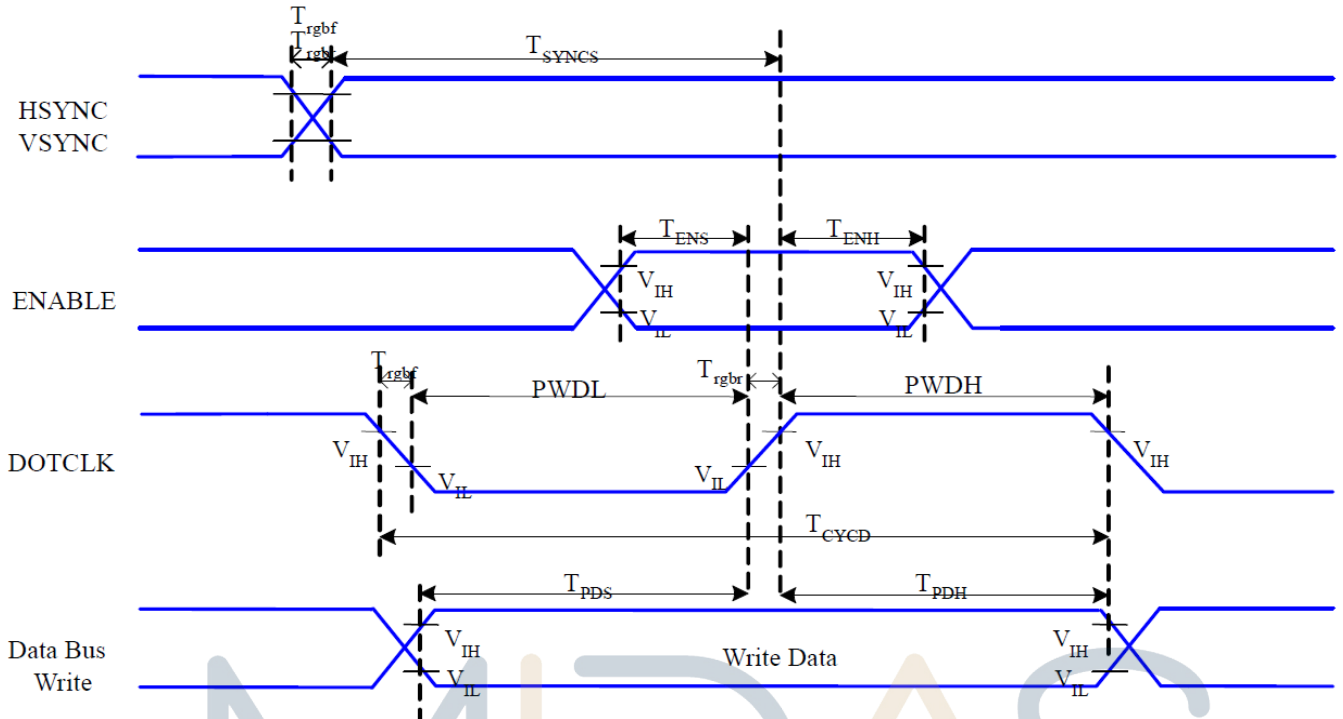


Figure6-4-1 RGB Interface Timing Characteristics

$VDDI=1.65$ to $3.3V$, $VDD=2.4$ to $3.3V$, $AGND=DGND=0V$, $Ta= -30$ to $70\text{ }^{\circ}C$

Signal	Symbol	Parameter	Min	Max	Unit	Description
HSYNC, VSYNC	T_{SYNCS}	VSYNC, HSYNC Setup Time	30		ns	
ENABLE	T_{ENS}	Enable Setup Time	25		ns	
	T_{ENH}	Enable Hold Time	25		ns	
DOTCLK	PWDH	DOTCLK High-level Pulse Width	60		ns	
	PWDL	DOTCLK Low-level Pulse Width	60		ns	
	T_{CYCD}	DOTCLK Cycle Time	120		ns	
	T_{rghr} T_{rghf}	DOTCLK Rise/Fall time		20	ns	
DB	T_{PDS}	PD Data Setup Time	50		ns	
	T_{PDH}	PD Data Hold Time	50		ns	

Table6-4-1 18/16 Bits RGB Interface Timing Characteristics



5. Reset Timing Characteristics

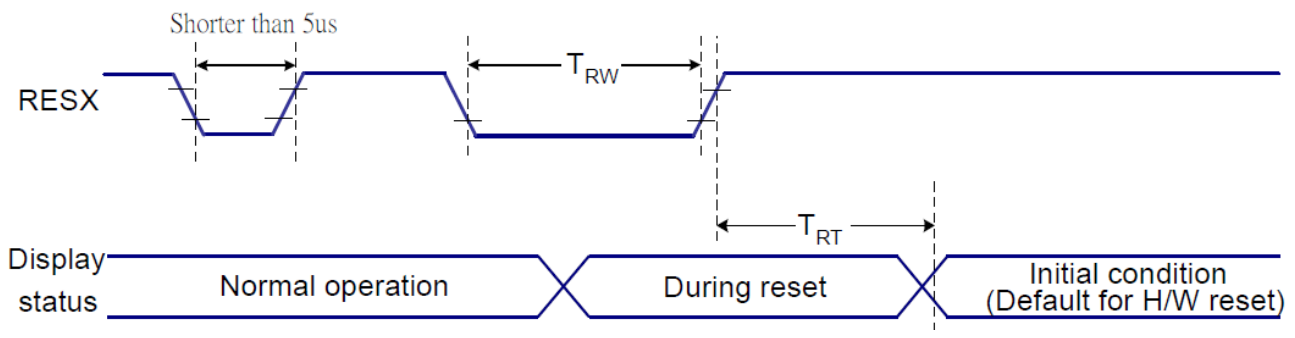


Figure6-5-1 Reset Timing

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta= -30 to 70 °C

Signal	Symbol	Parameter	Min	Max	Unit
RESX	T _{RW}	Reset pulse duration	10		us
	T _{RT}	Reset cancel		5 (Note 1, 5) 120 (Note 1, 6, 7)	ms

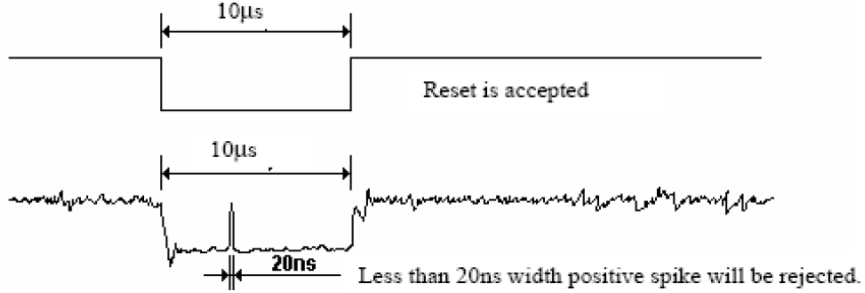
Notes:

- The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (t_{RT}) within 5 ms after a rising edge of RESX.
- Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below:

RESX	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode.) and then return to Default condition for Hardware Reset.

4. Spike Rejection also applies during a valid reset pulse as shown below:



- When Reset applied during Sleep In Mode.
- When Reset applied during Sleep Out Mode.
- It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.



CTP Specification

1. Electrical Characteristics

1.1 Absolute Maximum Rating

Item	Symbol	Min.	Max.	Unit	Note
Power Supply Voltage	VDD	2.7	3.6	V	--
I/O Digital Voltage	VDDIO	1.8	3.6	V	--

1.2 DC Electrical Characteristics (Ta=25°C)

Item	Min.	Typ.	Max.	Unit	Note
Power Supply Voltage/VDD	2.7	3.3	3.47	V	
I/O Digital Voltage/VDDIO	1.8	-	3.6		
Normal mode operating current	--	11	--	mA	
Sleep mode operating current	--	42	--	uA	
Monitor mode operating current	--	0.43	--	mA	
Digital Input low voltage/VIL	-0.3	--	0.3*VDDIO	V	
Digital Input high voltage/VIH	0.7*VDDIO	--	VDDIO	V	
Digital Output low voltage/VOL	--	--	0.3*VDDIO	V	
Digital Output high voltage/VOH	0.7*VDDIO	--	--	V	



1.3 AC Characteristics

AC Characteristics of Oscillators

Item	Symbol	Unit	Test Condition	Min.	Typ.	Max.	Note
OSC clock 1	fosc1	MHz	VDD3 = 2.8V; Ta=25°C	49	50	51	

Table 3-3 AC Characteristics of TX & RX

Item	Symbol	Test Condition	Min	Typ	Max	Unit	Note
TX acceptable clock	ftx		50	150	400	KHz	
TX output rise time	Ttxr		--	210	--	nS	
TX output fall time	Ttxf		--	210	--	nS	
RX input voltage	Trxi		1.2	--	1.6	V	

2. POWER ON/Reset Sequence

Reset should be pulled down to be low before powering on and powering down. I2C shouldn't be used by other devices during Reset time after VDD powering on (Trtp). INT signal will be sent to the host after initializing all parameters and then start to report points to the host. If Power is down, the voltage of supply must be below 0.3V and Tpd is more than 1ms.

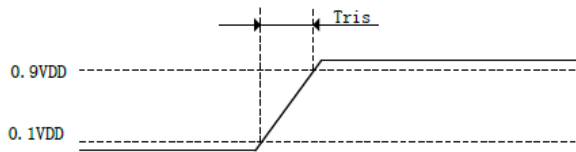


Figure 3-3 Power on time



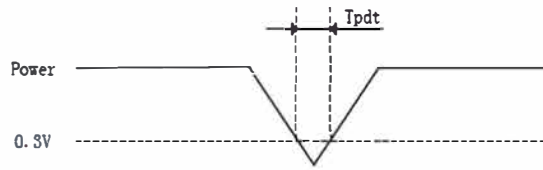


Figure 3-4 Power Cycle requirement

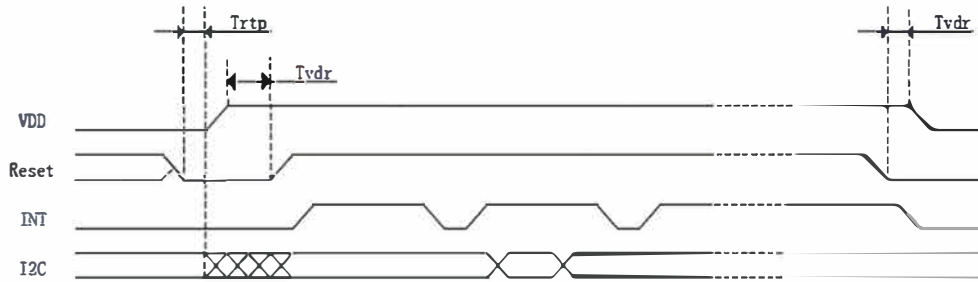


Figure 3-5 Power on Sequence

Reset time must be enough to guarantee reliable reset, the time of starting to report point after resetting approach to the time of starting to report point after powering on.

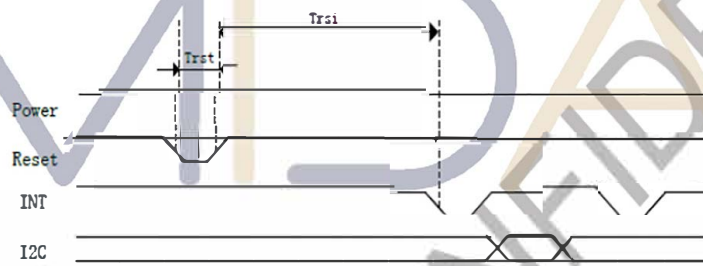


Table 3-5 Power on/Reset Sequence Parameters

Parameter	Description	Min	Max	Units
Tris	Rise time from 0.1VDD to 0.9VDD	--	5	ms
Tpdt	Time of the voltage of supply being below 0.3V	5	--	ms
Trtp	Time of resetting to be low before powering on	100	--	μs
Tvdr	Reset time after VDD powering on	1	--	ms
Trsi	Time of starting to report point after resetting	--	200	ms
Trst	Reset time	1	--	ms

3. I2C Timing

FT5436 supports the I2C interfaces, which can be used by a host processor or other devices.

The I2C is always configured in the Slave mode. The data transfer format is shown in **Figure 2-4**.

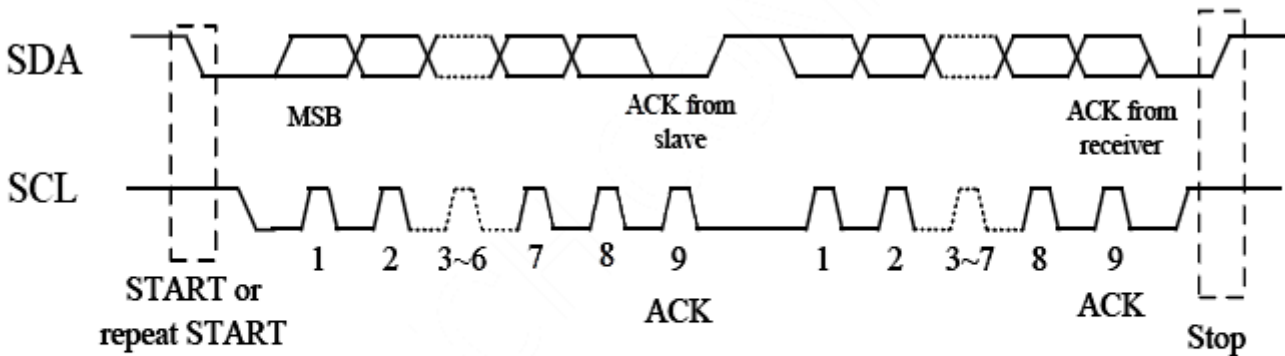


Figure 2-4 I2C Serial Data Transfer Format

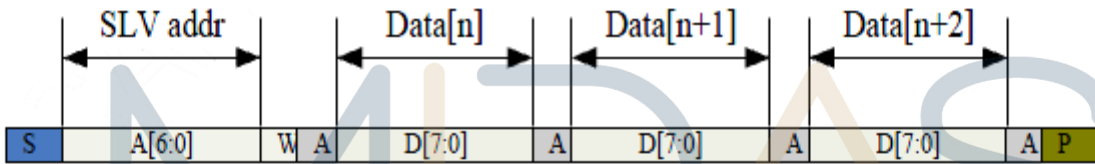


Figure 2-5 I2C master write, slave read

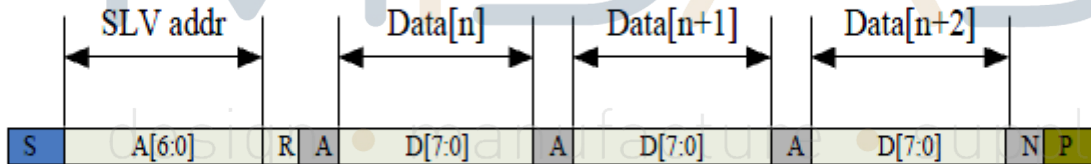


Figure 2-6 I2C master read, slave write

Table 2-1 lists the meanings of the mnemonics used in the above figures.

Table 2-1 Mnemonics Description



Mnemonics	Description
S	I2C Start or I2C Restart
A[6:0]	Slave address
R/ W	READ/WRITE bit, '1' for read, '0' for write
A(N)	ACK(NACK) bit
P	STOP: the indication of the end of a packet (if this bit is missing, S will indicate the end of the current packet and the beginning of the next packet)

I2C Interface Timing Characteristics is shown in Table 2-2.

Table 2-2 I2C Timing Characteristics

Parameter	Min	Max	Unit
SCL frequency	0	400	KHz
Bus free time between a STOP and START condition	1.3		us
Hold time (repeated) START condition	0.6		us
Data setup time	100		ns
Setup time for a repeated START condition	0.6		us
Setup Time for STOP condition	0.6		us

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LCD Module Out-Going Quality Level

1. VISUAL & FUNCTION INSPECTION STANDARD

1.1 Inspection conditions

Inspection performed under the following conditions is recommended.

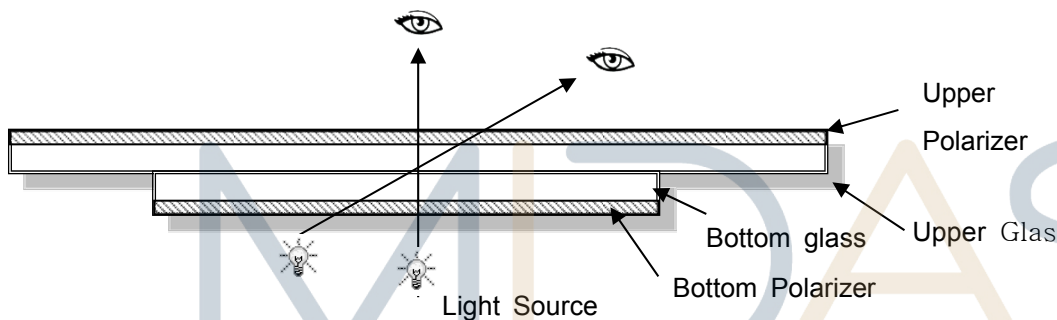
Temperature : $25\pm 5^{\circ}\text{C}$

Humidity : $65\%\pm 10\%\text{RH}$

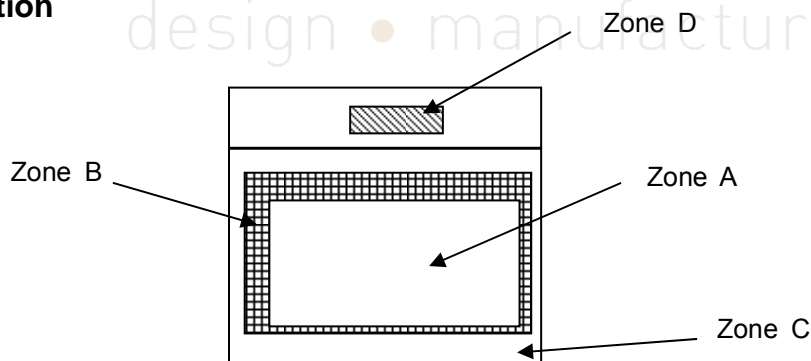
Viewing Angle : Normal viewing Angle.

Illumination: Single fluorescent lamp (300 to 700Lux)

Viewing distance:30-50cm



1.2 Definition



Zone A : Effective Viewing Area(Character or Digit can be seen)

Zone B : Viewing Area except Zone A

Zone C : Outside (Zone A+Zone B) which can not be seen after assembly by customer .)

Zone D : IC Bonding Area

Note:

As a general rule ,visual defects in Zone C can be ignored when it doesn't effect product function or appearance after assembly by customer



1.3 Sampling Plan

According to GB/T 2828.1-2003 ; , normal inspection, Class II

AQL:

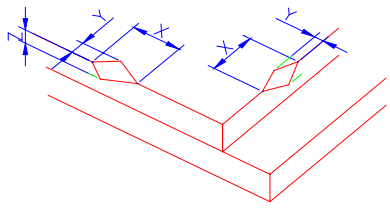
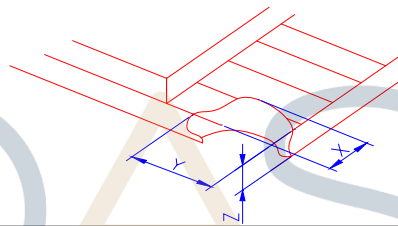
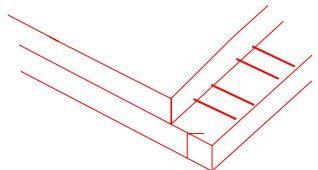
Major defect	Minor defect
0.65	1.5

LCD: Liquid Crystal Display , TP: Touch Panel , LCM: Liquid Crystal Module

No	Items to be inspected	Criteria	Classification of defects
1	Functional defects	1) No display, Open or miss line 2) Display abnormally, Short 3) Backlight no lighting, abnormal lighting. 4) TP no function	Major
2	Missing	Missing component	
3	Outline dimension	Overall outline dimension beyond the drawing is not allowed	Minor
4	Color tone	Color unevenness, refer to limited sample	
5	Spot Line defect	Light dot, Dim spot, Polarizer Bubble ; Polarizer accidented spot.	
6	Soldering appearance	Good soldering , Peeling off is not allowed.	
7	LCD/Polarizer/TP	Black/White spot/line, scratch, crack, etc.	

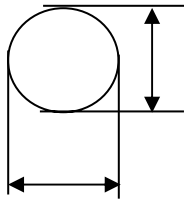


1.4 Criteria (Visual)

Number	Items	Criteria(mm)						
1.0 LCD Crack/Broken NOTE: X: Length Y: Width Z: Height L: Length of IT O, T: Height of LCD	(1) The edge of LCD broken	 <table border="1" data-bbox="758 667 1455 817"> <thead> <tr> <th>X</th> <th>Y</th> <th>Z</th> </tr> </thead> <tbody> <tr> <td>≤3.0mm</td> <td><Inner border line of the seal</td> <td>≤T</td> </tr> </tbody> </table>	X	Y	Z	≤3.0mm	<Inner border line of the seal	≤T
	X	Y	Z					
	≤3.0mm	<Inner border line of the seal	≤T					
(2) LCD corner broken	 <table border="1" data-bbox="813 1120 1396 1220"> <thead> <tr> <th>X</th> <th>Y</th> <th>Z</th> </tr> </thead> <tbody> <tr> <td>≤3.0mm</td> <td>≤L</td> <td>≤T</td> </tr> </tbody> </table>	X	Y	Z	≤3.0mm	≤L	≤T	
X	Y	Z						
≤3.0mm	≤L	≤T						
(3) LCD crack	 <p style="text-align: center;">Crack Not allowed</p>							



Spot defect



Y

X

$$\Phi = (X+Y)/2$$

① light dot (LCD/TP/Polarizer black/white spot , light dot, pinhole, dent, stain)

Zone Size (mm)	Acceptable Qty		
	A	B	C
$\Phi \leq 0.10$	Ignore		
$0.10 < \Phi \leq 0.25$	3(distance $\geq 10\text{mm}$)		
$0.25 < \Phi \leq 0.3$	2		
$\Phi > 0.35$	0		

② Dim spot (LCD/TP/Polarizer dim dot, light leakage, dark spot)

Zone Size (mm)	Acceptable Qty		
	A	B	C
$\Phi \leq 0.1$	Ignore		
$0.10 < \Phi \leq 0.25$	3(distance $\geq 10\text{mm}$)		
$0.25 < \Phi \leq 0.3$	2		
$\Phi > 0.35$	0		

③ Polarizer accidented spot

Zone Size (mm)	Acceptable Qty		
	A	B	C
$\Phi \leq 0.2$	Ignore		
$0.3 < \Phi \leq 0.5$	2(distance $\geq 10\text{mm}$)		
$\Phi > 0.5$	0		

④ Pixel bad points (light dot, Dim dot, color dot)

Zone Size (mm)	Acceptable Qty		
	A	B	C
$\Phi \leq 0.1$	Ignore		
$0.15 < \Phi \leq 0.25$	2(distance $\geq 10\text{mm}$)		
$\Phi > 0.3$	0		

⑤ Polarizer Bubble

Zone Size (mm)	Acceptable Qty		
	A	B	C
$\Phi \leq 0.2$	Ignore		
$0.3 < \Phi \leq 0.4$	3(distance $\geq 10\text{mm}$)		
$0.5 < \Phi \leq 0.6$	2		
$0.6 < \Phi$	0		

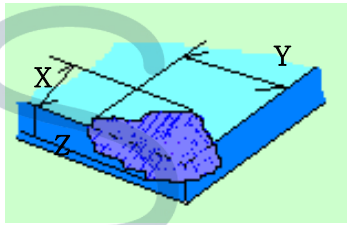
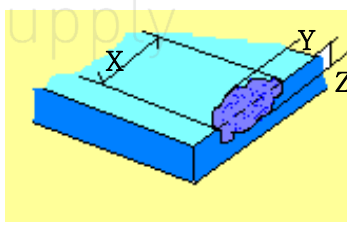
2.0



3.0	Line defect (LCD/TP /Polarizer backlight black/white line, scratch, stain)	Width(mm)	Length(m)	Acceptable Qty		
				A	B	C
		$\Phi \leq 0.05$	Ignore	Ignore		
		$0.05 < W \leq 0.06$	$L \leq 4.0$	$N \leq 3$		
		$0.07 < W \leq 0.08$	$L \leq 3.0$	$N \leq 2$		
	$0.08 < W$	Define as spot defect				
4.0	Electronic Components SMT	Not allow missing parts, solderless connection, cold solder joint, mismatch, The positive and negative polarity opposite				
5.0	Display color & Brightness	<p>1. Color: Measuring the color coordinates, The measurement standard according to the datasheet or samples.</p> <p>2. Brightness: Measuring the brightness of White screen, The measurement standard according to the datasheet or Samples.</p>				
6.0	LCD Mura	By 5% ND filter invisible.				

7.0	CTP Related	CTP Cover sensor accidented black/white spot	Size Φ (mm)	Acceptable Qty			
				A	B	C	
			$\Phi \leq 0.1$	Ignore			
			$0.1 < \Phi \leq 0.2$	3 (distance ≥ 10 mm)			
			$0.20 < \Phi \leq 0.25$	2			
			$\Phi > 0.3$	0			
		CTP Cover scratch	Width(mm)	Ignore (mm)	Acceptable Qty		
					A	B	C
			$\Phi \leq 0.05$	Ignore	Ignore		
			$0.05 < W \leq 0.06$	$L \leq 4.0$	$N \leq 3$		
$0.07 < W \leq 0.08$	$L \leq 3.0$		$N \leq 2$				
	$0.08 < W$	Define as spot defect					



		CTP Cover Pinhole/ Lack of ink	<table border="1"> <tr> <td rowspan="2">Zone Size (mm)</td> <td colspan="2">Acceptable Qty</td> </tr> <tr> <td colspan="2">C</td> </tr> <tr> <td>$\Phi \leq 0.1$</td> <td colspan="2">Ignore</td> </tr> <tr> <td>$0.1 < \Phi \leq 0.2$</td> <td colspan="2">3(distance ≥ 10mm)</td> </tr> <tr> <td>$0.25 < \Phi \leq 0.3$</td> <td colspan="2">2</td> </tr> <tr> <td>$\Phi > 0.35$</td> <td colspan="2">0</td> </tr> </table>	Zone Size (mm)	Acceptable Qty		C		$\Phi \leq 0.1$	Ignore		$0.1 < \Phi \leq 0.2$	3(distance ≥ 10 mm)		$0.25 < \Phi \leq 0.3$	2		$\Phi > 0.35$	0	
Zone Size (mm)	Acceptable Qty																			
	C																			
$\Phi \leq 0.1$	Ignore																			
$0.1 < \Phi \leq 0.2$	3(distance ≥ 10 mm)																			
$0.25 < \Phi \leq 0.3$	2																			
$\Phi > 0.35$	0																			
		CTP Bonding bubble/ accident spot	<table border="1"> <tr> <td rowspan="2">Size Φ(mm)</td> <td colspan="2">Acceptable Qty</td> </tr> <tr> <td>A</td> <td>B</td> </tr> <tr> <td>$\Phi \leq 0.1$</td> <td colspan="2">Ignore</td> </tr> <tr> <td>$0.15 < \Phi \leq 0.2$</td> <td colspan="2">3(distance ≥ 10mm)</td> </tr> <tr> <td>$0.2 < \Phi \leq 0.25$</td> <td colspan="2">2</td> </tr> <tr> <td>$\Phi > 0.25$</td> <td colspan="2">0</td> </tr> </table>	Size Φ (mm)	Acceptable Qty		A	B	$\Phi \leq 0.1$	Ignore		$0.15 < \Phi \leq 0.2$	3(distance ≥ 10 mm)		$0.2 < \Phi \leq 0.25$	2		$\Phi > 0.25$	0	
Size Φ (mm)	Acceptable Qty																			
	A	B																		
$\Phi \leq 0.1$	Ignore																			
$0.15 < \Phi \leq 0.2$	3(distance ≥ 10 mm)																			
$0.2 < \Phi \leq 0.25$	2																			
$\Phi > 0.25$	0																			
		Assembly deflection	beyond the edge of backlight ≤ 0.2 mm																	
		TP cover broken X : length Y : width Z : height	<table border="1"> <tr> <td>X</td> <td>Y</td> <td>Z</td> </tr> <tr> <td>$X \leq 0.5$mm</td> <td>$Y \leq 0.5$mm</td> <td>$Z < \text{cover thickness}$</td> </tr> </table> <p>* Circuitry broken is not allowed.</p> 	X	Y	Z	$X \leq 0.5$ mm	$Y \leq 0.5$ mm	$Z < \text{cover thickness}$											
X	Y	Z																		
$X \leq 0.5$ mm	$Y \leq 0.5$ mm	$Z < \text{cover thickness}$																		
		TP cover broken X : length Y : width Z : height	<table border="1"> <tr> <td>X</td> <td>Y</td> <td>Z</td> </tr> <tr> <td>$X \leq 0.3$mm</td> <td>$Y \leq 0.3$mm</td> <td>$Z < \text{LCD thickness}$</td> </tr> </table> <p>* Circuitry broken is not allowed.</p> 	X	Y	Z	$X \leq 0.3$ mm	$Y \leq 0.3$ mm	$Z < \text{LCD thickness}$											
X	Y	Z																		
$X \leq 0.3$ mm	$Y \leq 0.3$ mm	$Z < \text{LCD thickness}$																		

Criteria (functional items)

Number	Items	Criteria (mm)
1	No display	Not allowed
2	Missing segment	Not allowed
3	Short	Not allowed
4	Backlight no lighting	Not allowed
5	TP no function	Not allowed



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Reliability Test Result

Item	Condition	Inspection after test
High Temperature Operating	70℃,96H	Inspection after 2~4hours storage at room temperature, the sample shall be free from defects: 1.Air bubble in the LCD; 2.Non-display; 3.Missing segments/line; 4.Glass crack; 5.Current IDD is twice higher than initial value.
Low Temperature Operating	-20℃, 96HR	
High Temperature Storage	80℃, 96HR	
Low Temperature Storage	-30℃, 96HR	
High Temperature & High Humidity Operating	+60℃, 90% RH ,96 hours.	
Thermal Shock (Non-operation)	-10℃,30 min ↔ 60℃,30 min, Change time:5min 20CYC.	
ESD test	C=150pF, R=330,5points/panel Air:±8KV, 5times; Contact:±6KV, 5 times; (Environment: 15℃~35℃, 30%~60%).	
Vibration (Non-operation)	Frequency range:10~55Hz, Stroke:1.5mm Sweep:10Hz~55Hz~10Hz 2 hours for each direction of X.Y.Z. (6 hours for total) (Package condition).	
Box Drop Test	1 Corner 3 Edges 6 faces,80cm(MEDIUM BOX)	

Remark:

- 1.The test samples should be applied to only one test item.
- 2.Sample size for each test item is 5~10pcs.
- 3.For Damp Proof Test, Pure water(Resistance > 10MΩ) should be used.
- 4.In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judged as a good part.
- 5.Failure Judgment Criterion: Basic Specification, Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.
6. The color fading mura of polarizing filter should not care.



Cautions and Handling Precautions

1. Handling and Operating the Module

- (1) When the module is assembled, it should be attached to the system firmly.
Do not warp or twist the module during assembly work.
- (2) Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.
- (3) Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.
- (4) Do not allow drops of water or chemicals to remain on the display surface.
If you have the droplets for a long time, staining and discoloration may occur.
- (5) If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.
- (6) The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane.
Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.
- (7) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.
- (8) Protect the module from static; it may cause damage to the CMOS ICs.
- (9) Use finger-stalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.
- (10) Do not disassemble the module.
- (11) Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.
- (12) Pins of I/F connector shall not be touched directly with bare hands.
- (13) Do not connect, disconnect the module in the "Power ON" condition.
- (14) Power supply should always be turned on/off by the item 6.1 Power On Sequence & 6.2 Power Off Sequence

2. Storage and Transportation.

- (1) Do not leave the panel in high temperature, and high humidity for a long time.
It is highly recommended to store the module with temperature from 0 to 35 °C and relative humidity of less than 70%
- (2) Do not store the TFT-LCD module in direct sunlight.
- (3) The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.
- (4) It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module.
In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.
- (5) This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.

